

Title (en)  
DEVICE AND METHOD FOR INJECTION MOLDING

Title (de)  
VORRICHTUNG UND VERFAHREN ZUM SPRITZGIESSEN

Title (fr)  
DISPOSITIF ET PROCÉDÉ DE MOULAGE PAR INJECTION

Publication  
**EP 4126496 A1 20230208 (DE)**

Application  
**EP 20717142 A 20200401**

Priority  
EP 2020059281 W 20200401

Abstract (en)  
[origin: WO2021197599A1] The invention particularly relates to a device for injection molding, in particularly micro-injection molding, at least comprising a mold having a first mold half and a second mold half, the first mold half and the second mold half defining an injection molding chamber in the closed state of the mold, the device also comprising an insert in the injection molding chamber.

IPC 8 full level  
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Citation (search report)  
See references of WO 2021197599A1

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KH MA MD TN

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